

REV.	ECN.NO.	DATE
A	RELEASED	04/19-'17
F	Modify molding structure	11/24-'21
G	Modify Contact Structure	05/06-'25

NOTES:

*Material

Housing: LCP, UL 94V-0.
Contact: Brass.
Plating: Au Plating On Contact Area;
Sn(100u" Min.) Plating On Solder Tail;
Ni(50u" Min.) Underplating Overall;

*Mechanical

Insertion Force: 1.15N Max per contact pair;
Withdrawal Force: 0.15N Min per contact pair;
Contact Retention Force: 3.5N Min per contact;
Durability: 50 cycles.

*Electrical Specification

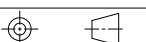
Current Rating : 1.1 Ampere.
Contact Resistance : 30mΩ Max.
Insulation Resistance : 1000MΩ Min, At 500V AC.

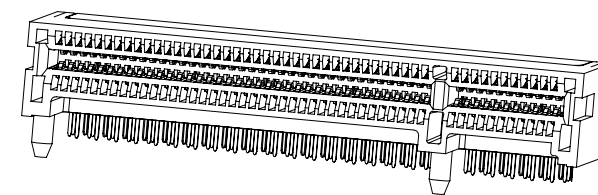
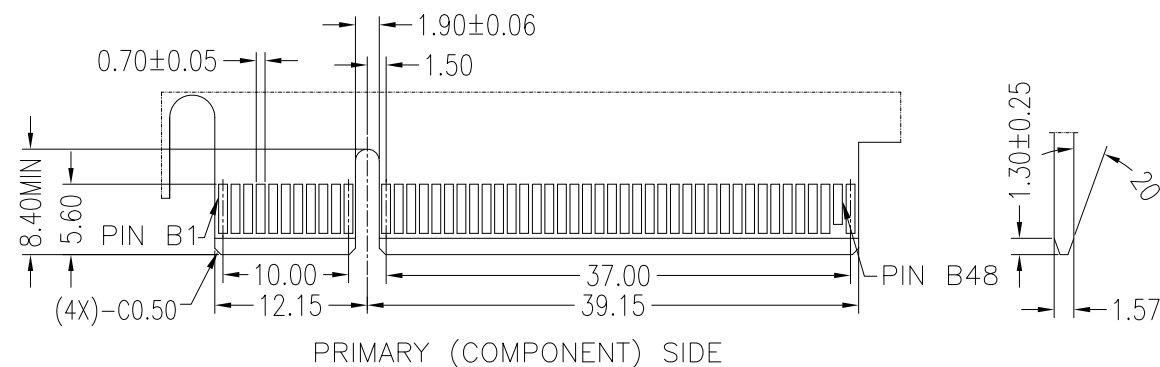
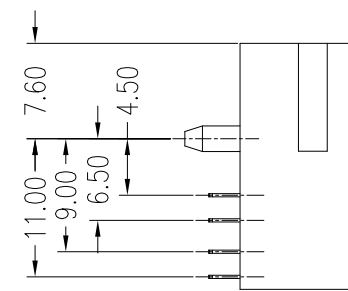
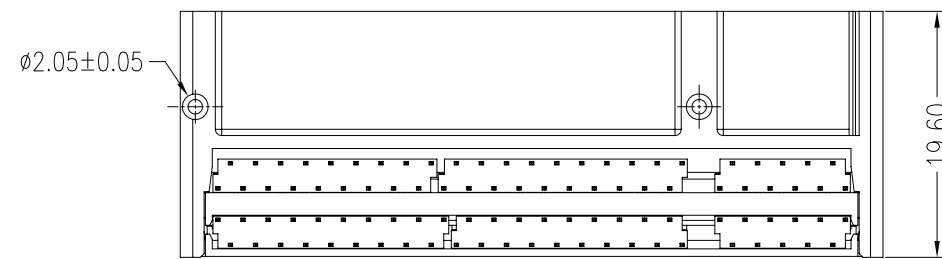
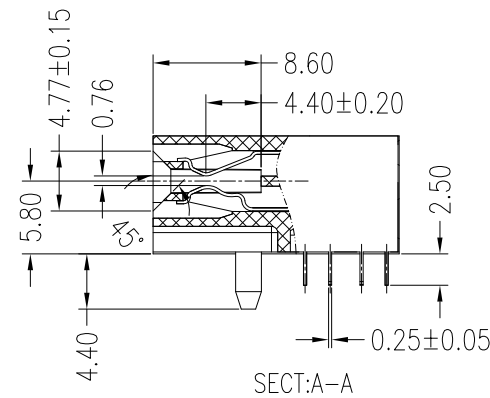
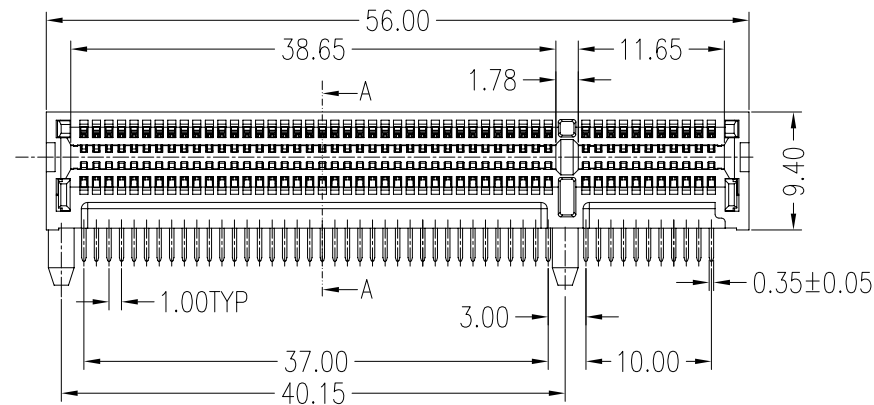
*Environmental

Operating Temperature : -55℃ to +105℃

*How to Order:

Series NO. _____
Number of Contacts _____
Au: A:1u" D:15u" F:30u" _____
L: LCP _____
1: Black _____
Blank: No Mark
W: Winning Mark
U: Lead Free
7: DIP 2.50(GEN3)(Right key)
B: Brass

REV	Modify Contact Structure										
Units	mm	Scale	10: 9	Drawing By	Date	 连兴旺电子(深圳)有限公司 LXWCONN ELECTRONICS (SHENZHEN) CO., LTD					
Tolerance Unless Otherwise Specified				CLJ	05/06-'25						
.X ~ ±0.35				Reviewed By	Date	Date	05/06-'25	Title	PCI EXPRESS R/A DIP TYPE (GEN3) 98PIN (Right key)		
.XX ~ ±0.25				Charles	05/07-'25	Sheet	1 of 1				
.XXX ~ ±0.15				Approval By	Date	Third Angle Projection					
Angle ~ ± 3°				Eric	05/07-'25		Drawing No.		WPRS-098AL1B7U	REV	G



3D VIEW

